

## Low-pressure plasma system V10-G

### Efficient batch system for removal of photoresist



*The low-pressure plasma system V10-G is equipped with a sliding door and a process chamber made of quartz glass and is also suitable for the cleaning of wafers.*

The batch system V10-G is designed for the removal of photoresists. Furthermore it can be optimally used for the cleaning of wafers.

#### Areas of application

- Ideal system for removing photoresist layers (also SU-8) after dry processes like RIE or Ion Beam etching as well as after high dose implant processes
- Silicon wafers or other substrate cleaning prior wet processing to achieve a better wettability for an uniform and efficient result
- Applicable for processes in MEMS and nanotechnology
- Polymer removal e.g. after Bosch processes
- Removal of organic sacrificial layers
- Conditioning of bioactive compounds

#### System features

- Process chamber: quartz glass
- Sliding door
- PLC control: SPS (S7-300)
- Resistive touch screen panel with Windows operating system (also operable with gloves)
- Automatic and manual operation
- Display of all process relevant parameters
- Individual access authorization via user groups
- Archiving of all processes
- Remote maintenance (VPN)
- Ethernet interface

#### Options

- Vacuum pump
- Ozone trap
- Up to two additional gas inlets
- Soft start and slow vent
- Faraday cage
- Process pressure control valve

#### Technical data

Dimensions of the system (W x D x H): 720 x 820 x 820 mm

Dimensions of the chamber (Ø x D): 215 x 260 mm

Plasma excitation frequency: Microwave (2.45 GHz)

Microwave power: 50-600 W

Gas inlets with mass flow controller: 1 channel

Power supply: 400 V, 50/60 Hz

Power input (without vacuum pump): 1.5 kVA

Vacuum gauge: Pirani

Weight: 150 kg



#### PiNK GmbH Thermosysteme

Am Kessler 6  
97877 Wertheim  
Germany  
T +49 (0) 93 42 919-0  
F +49 (0) 93 42 919-111  
plasma-finish@pink.de  
www.pink.de